

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
 Stylesheet Version v1.2

EPAS ID: PAT5021478

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
HUAN-SHENG WEI	11/28/2016
HUNG-LI CHIANG	11/28/2016
CHIA-WEN LIU	11/28/2016
YI-MING SHEU	11/25/2016
ZHIQIANG WU	11/28/2016
CHUNG-CHENG WU	11/28/2016
YING-KEUNG LEUNG	11/28/2016
RECEIVING PARTY DATA	
Name:	TAIWAN SEMICONDUCTOR MANUFACTURING CO., LTD.
Street Address:	NO. 8, LI-HSIN RD. 6
Internal Address:	SCIENCE-BASED INDUSTRIAL PARK
City:	HSIN-CHU
State/Country:	TAIWAN
Postal Code:	300-77
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	16016748
CORRESPONDENCE DATA	
Fax Number:	(214)200-0853
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
Phone:	214-651-5000
Email:	ipdocketing@haynesboone.com
Correspondent Name:	HAYNES AND BOONE, LLP IP SECTION
Address Line 1:	2323 VICTORY AVENUE
Address Line 2:	SUITE 700
Address Line 4:	DALLAS, TEXAS 75219
ATTORNEY DOCKET NUMBER:	20160617 / 24061.3417US02
NAME OF SUBMITTER:	JANIE MARTINEZ-HOLM
SIGNATURE:	/Janie Martinez-Holm/

PATENT

DATE SIGNED:	06/25/2018
Total Attachments: 3 source=24061-3417US02_Assignment_Parent#page1.tif source=24061-3417US02_Assignment_Parent#page2.tif source=24061-3417US02_Assignment_Parent#page3.tif	

ASSIGNMENT

WHEREAS, we,

- | | | | |
|-----|-------------------------|----|-------------------------------|
| (1) | Huan-Sheng Wei | of | Taipei City, Taiwan (R.O.C.) |
| (2) | Hung-Li Chiang | of | Taipei City, Taiwan (R.O.C.) |
| (3) | Chia-Wen Liu | of | Taipei City, Taiwan (R.O.C.) |
| (4) | Yi-Ming Sheu | of | Hsinchu, Taiwan (R.O.C.) |
| (5) | Zhiqiang Wu | of | Chubei, Taiwan (R.O.C.) |
| (6) | Chung-Cheng Wu | of | Ju-Bei City, Taiwan (R.O.C.) |
| (7) | Ying-Keung Leung | of | Hsinchu City, Taiwan (R.O.C.) |

have invented certain improvements in

MULTI-GATE DEVICE AND METHOD OF FABRICATION THEREOF

for which we have executed an application for Letters Patent of the United States of America,

 X of even date filed herewith; and filed on and assigned application number ; and

WHEREAS, we authorize the attorney of record to update this document to include Patent Office information as deemed necessary (i.e., filing date, serial number, etc.);

WHEREAS, **Taiwan Semiconductor Manufacturing Co., Ltd., ("TSMC")**, No. 8, Li-Hsin Rd. 6, Science-Based Industrial Park Hsin-Chu, Taiwan 300-77, Republic of China. is desirous of obtaining the entire right, title, and interest in, to and under the said invention and the said application in the United States of America and in any and all countries foreign thereto;

NOW, THEREFORE, for good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, and other good and valuable consideration, we have sold, assigned, transferred and set over, and by these presents do hereby sell, assign, transfer and set over, unto the said TSMC, its successors, legal representatives, and assigns, the entire right, title, and interest in, to and under the said invention, and the said application, and all divisional, renewal, substitutional, and continuing applications thereof, and all Letters Patent of the United States of America which may be granted thereon and all reissues and extensions thereof, and all applications for Letters Patent which may be filed for said invention in any country or countries foreign to the United States of America, and all extensions, renewals, and reissues thereof, and all prior patents and patent applications from which a filing priority of the above-described patent application may be obtained, including the right to collect past damages; and we hereby authorize and request the Commissioner of Patents of the United States of America, and any official of any country or countries foreign to the United States of America, whose

Docket No.: P20160617US00 / 24061.3417US01
Customer No.: 000042717

duty it is to issue patents on applications as aforesaid, to issue all Letters Patent for said invention to the said TSMC, its successors, legal representatives and assigns, in accordance with the terms of this instrument.

AND WE HEREBY covenant that we have full right to convey the entire interest herein assigned, and that we have not executed, and will not execute, any agreement in conflict herewith.

AND WE HEREBY further covenant and agree that we will communicate to said TSMC, its successors, legal representatives and assigns, any facts known to us respecting said invention, and testify in any legal proceedings, sign all lawful papers, execute all divisional, renewal, substitutional, continuing, and reissue applications, make all rightful declarations and/or oaths and generally do everything possible to aid the said TSMC, its successors, legal representatives and assigns, to obtain and enforce proper patent protection for said invention in all countries.

Inventor Name: **Huan-Sheng Wei**

Residence Address: 4F., No.6, Dadao Rd., Xinyi Dist., Taipei City 110, Taiwan (R.O.C.)

Dated: 2016/11/28

Huan-Sheng Wei
Inventor Signature

Inventor Name: **Hung-Li Chiang**

Residence Address: 12F., No.87, Ln. 16, Xinyan Rd., Wenshan Dist., Taipei City 116, Taiwan (R.O.C.)

Dated: 2016/11/28

Hung-Li Chiang
Inventor Signature

Inventor Name: **Chia-Wen Liu**

Residence Address: 4F., No.14, Ln. 23, Nanshen Rd., Nangang Dist., Taipei City 115, Taiwan (R.O.C.)

Dated: 2016.11.28

Chia-Wen Liu
Inventor Signature

Docket No.: P20160617US00 / 24061.3417US01
Customer No.: 000042717

Inventor Name: **Yi-Ming Sheu**

Residence Address: No. 24, Lane 136, Junghe Rd., Hsinchu 300 Taiwan (R.O.C.)

Dated: 2016/11/25

Yi-Ming Sheu
Inventor Signature

Inventor Name: **Zhiqiang Wu**

Residence Address: 22F, No. 533 Hsin Long Rd Section 1, Chubei, Hsinchu County, Taiwan (R.O.C.)

Dated: 2016/11/28

Zhiqiang Wu
Inventor Signature

Inventor Name: **Chung-Cheng Wu**

Residence Address: No 2, Alley 1, Ln 232, Chung-San Rd., Ju-Bei City, Hsinchu County, Taiwan (R.O.C.)

Dated: 2016/11/28

Chung-Cheng Wu
Inventor Signature

Inventor Name: **Ying-Keung Leung**

Residence Address: 4F., No.127, Puding 3rd Rd., East Dist., Hsinchu City 300, Taiwan (R.O.C.)

Dated: 2016/11/29

Ying-Keung Leung
Inventor Signature